

## Excellent Integrated System Limited

Stocking Distributor

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[IXYS Corporation](#)

[FBO16-12N](#)

For any questions, you can email us directly:

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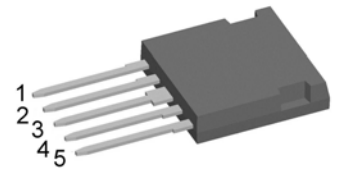
## Standard Rectifier

<b>1~ Rectifier</b>	
$V_{RRM}$	= 1200 V
$I_{DAV}$	= 20 A
$I_{FSM}$	= 150 A


### 1~ Rectifier Bridge

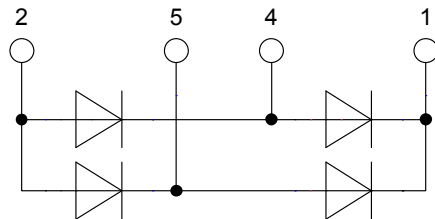
Part number

**FBO16-12N**



Backside: isolated

 E72873



#### Features / Advantages:

- Planar passivated chips
- Very low leakage current
- Very low forward voltage drop
- Improved thermal behaviour

#### Applications:

- Diode Bridge for main rectification

#### Package: i4-Pac

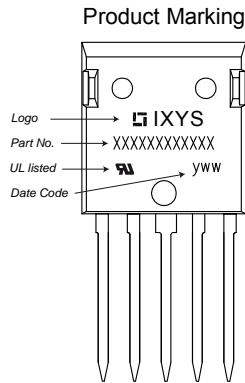
- Isolation Voltage: 3000V~
- Industry convenient outline
- RoHS compliant
- Epoxy meets UL 94V-0
- Soldering pins for PCB mounting
- Backside: DCB ceramic
- Reduced weight
- Advanced power cycling

Rectifier				Ratings			Unit
Symbol	Definition	Conditions	min.	typ.	max.		
$V_{RSM}$	max. non-repetitive reverse blocking voltage		$T_{VJ} = 25^{\circ}C$			1300	V
$V_{RRM}$	max. repetitive reverse blocking voltage		$T_{VJ} = 25^{\circ}C$			1200	V
$I_R$	reverse current, drain current	$V_R = 1200\text{ V}$	$T_{VJ} = 25^{\circ}C$			10	$\mu A$
		$V_R = 1200\text{ V}$	$T_{VJ} = 150^{\circ}C$			1	mA
$V_F$	forward voltage drop	$I_F = 10\text{ A}$	$T_{VJ} = 25^{\circ}C$			1.21	V
		$I_F = 20\text{ A}$				1.43	V
		$I_F = 10\text{ A}$	$T_{VJ} = 150^{\circ}C$			1.14	V
		$I_F = 20\text{ A}$				1.45	V
$I_{DAV}$	bridge output current	$T_C = 130^{\circ}C$ rectangular $d = 0.5$	$T_{VJ} = 175^{\circ}C$			20	A
$V_{F0}$	threshold voltage	} for power loss calculation only	$T_{VJ} = 175^{\circ}C$			0.81	V
$r_F$	slope resistance					32	m $\Omega$
$R_{thJC}$	thermal resistance junction to case					3	K/W
$R_{thCH}$	thermal resistance case to heatsink			0.20			K/W
$P_{tot}$	total power dissipation		$T_C = 25^{\circ}C$			50	W
$I_{FSM}$	max. forward surge current	$t = 10\text{ ms}; (50\text{ Hz}), \text{ sine}$	$T_{VJ} = 45^{\circ}C$			150	A
		$t = 8,3\text{ ms}; (60\text{ Hz}), \text{ sine}$	$V_R = 0\text{ V}$			160	A
		$t = 10\text{ ms}; (50\text{ Hz}), \text{ sine}$	$T_{VJ} = 150^{\circ}C$			130	A
		$t = 8,3\text{ ms}; (60\text{ Hz}), \text{ sine}$	$V_R = 0\text{ V}$			140	A
$I^2t$	value for fusing	$t = 10\text{ ms}; (50\text{ Hz}), \text{ sine}$	$T_{VJ} = 45^{\circ}C$			115	A <sup>2</sup> s
		$t = 8,3\text{ ms}; (60\text{ Hz}), \text{ sine}$	$V_R = 0\text{ V}$			105	A <sup>2</sup> s
		$t = 10\text{ ms}; (50\text{ Hz}), \text{ sine}$	$T_{VJ} = 150^{\circ}C$			85	A <sup>2</sup> s
		$t = 8,3\text{ ms}; (60\text{ Hz}), \text{ sine}$	$V_R = 0\text{ V}$			82	A <sup>2</sup> s
$C_J$	junction capacitance	$V_R = 400\text{ V}; f = 1\text{ MHz}$	$T_{VJ} = 25^{\circ}C$		4		pF



**FBO16-12N**

Package i4-Pac		Ratings				
Symbol	Definition	Conditions	min.	typ.	max.	Unit
$I_{RMS}$	RMS current	per terminal			35	A
$T_{stg}$	storage temperature		-55		150	°C
$T_{VJ}$	virtual junction temperature		-55		175	°C
<b>Weight</b>				9		g
$F_C$	mounting force with clip		20		120	N
$d_{Spp/App}$	creepage distance on surface   striking distance through air	terminal to terminal	1.7			mm
$d_{Spb/Apb}$		terminal to backside	5.1			mm
$V_{ISOL}$	isolation voltage	t = 1 second	3000			V
		t = 1 minute	2500			V

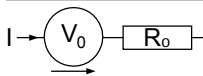


Ordering	Part Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	FBO16-12N	FBO16-12N	Tube	25	492310

**Equivalent Circuits for Simulation**

\* on die level

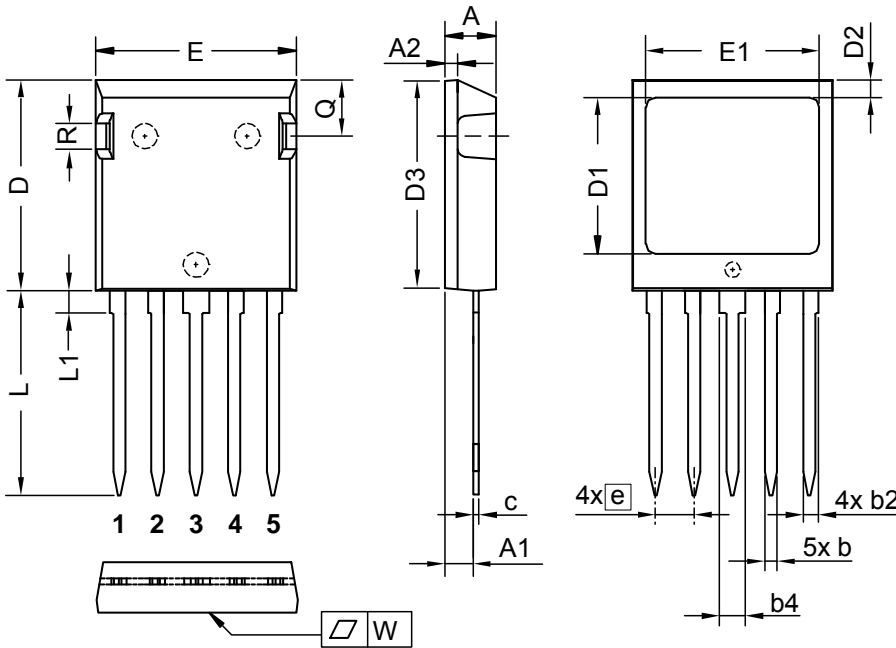
$T_{VJ} = 175^{\circ}C$



Rectifier

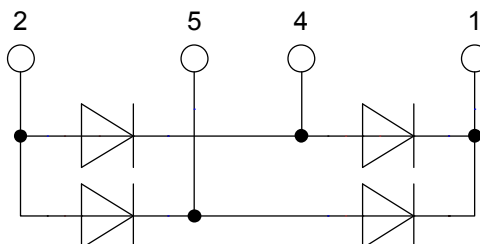
$V_{0\ max}$	threshold voltage	0.81	V
$R_{0\ max}$	slope resistance *	29	mΩ

Outlines i4-Pac



Dim.	Millimeter		Inches	
	min	max	min	max
A	4.83	5.21	0.190	0.205
A1	2.59	3.00	0.102	0.118
A2	1.17	2.16	0.046	0.085
b	1.14	1.40	0.045	0.055
b2	1.47	1.73	0.058	0.068
b4	2.54	2.79	0.100	0.110
c	0.51	0.74	0.020	0.029
D	20.80	21.34	0.819	0.840
D1	14.99	15.75	0.590	0.620
D2	1.65	2.03	0.065	0.080
D3	20.30	20.70	0.799	0.815
E	19.56	20.29	0.770	0.799
E1	16.76	17.53	0.660	0.690
e	3.81 BSC		0.150 BSC	
L	19.81	21.34	0.780	0.840
L1	2.11	2.59	0.083	0.102
Q	5.33	6.20	0.210	0.244
R	2.54	4.57	0.100	0.180
W	-	0.10	-	0.004

Die konvexe Form des Substrates ist typ. < 0.05 mm über der Kunststoffoberfläche der Bauteilunterseite  
The convexbow of substrate is typ. < 0.05 mm over plastic surface level of device bottom side



**Rectifier**

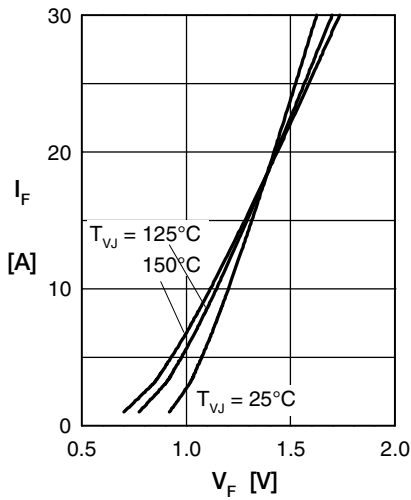


Fig. 1 Forward current versus voltage drop per diode

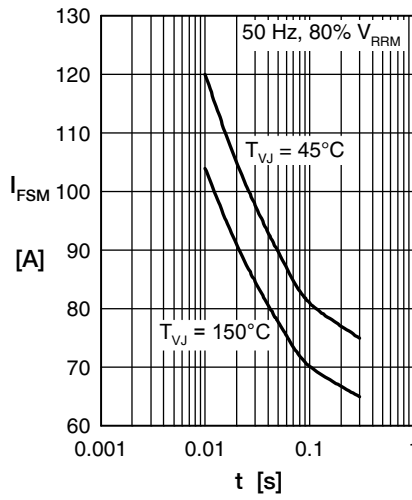


Fig. 2 Surge overload current

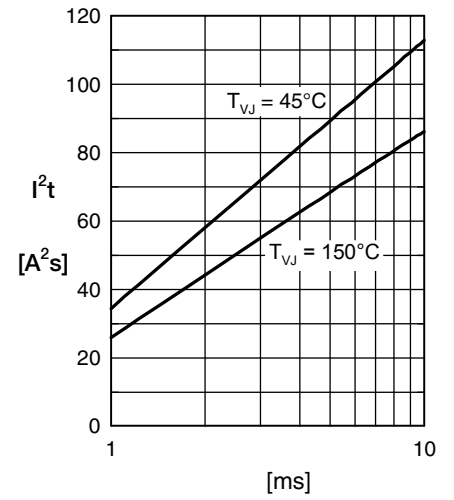


Fig. 3 I<sup>2</sup>t versus time per diode

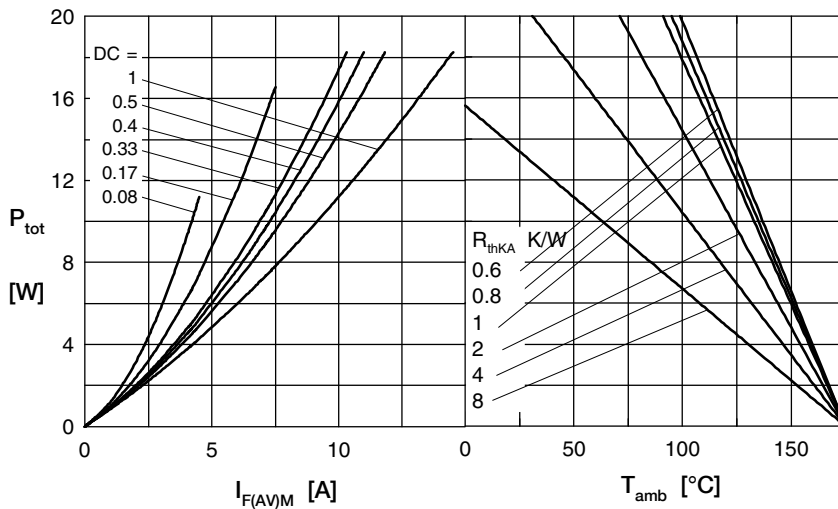


Fig. 4 Power dissipation vs. direct output current & ambient temperature

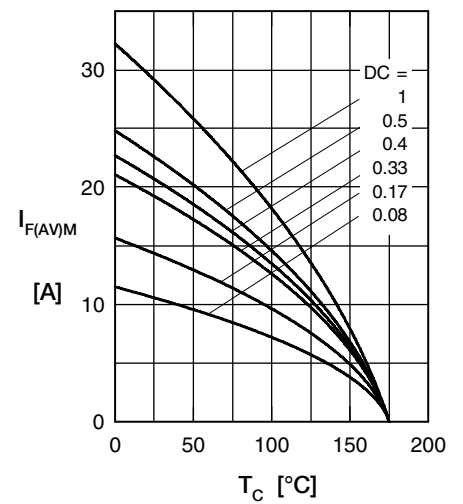


Fig. 5 Max. forward current vs. case temperature

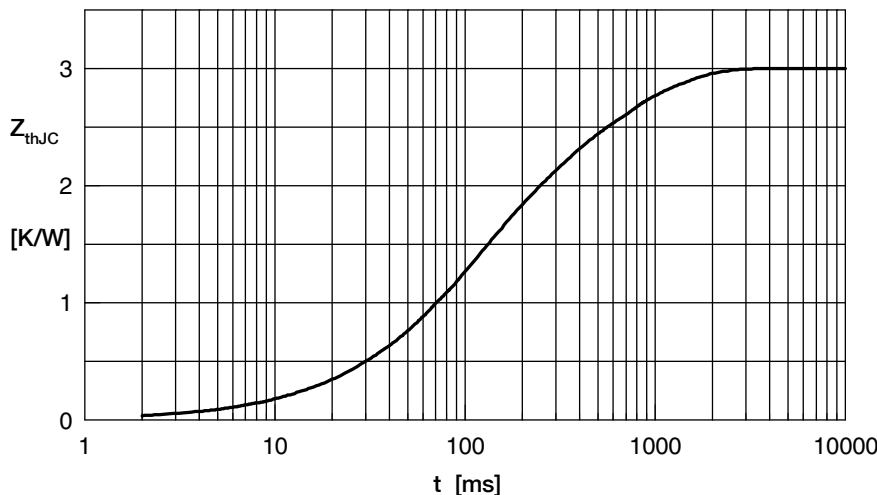


Fig. 6 Transient thermal impedance junction to case

Constants for  $Z_{thJC}$  calculation:

i	$R_{thi}$ (K/W)	$t_i$ (s)
1	1.359	0.1015
2	0.3286	0.1026
3	0.4651	0.4919
4	0.8473	0.62